

**Search Notes****Application/Control No.**

10/687,085

**Examiner**

Stephen W. Smoot

**Applicant(s)/Patent under Reexamination**

MAEDA, HIROSHI

**Art Unit**

2813

**SEARCHED**

Class	Subclass	Date	Examiner
438	108	1/12/2005	SWS
438	118	1/12/2005	SWS
438	126	1/12/2005	SWS
438	127	1/12/2005	SWS
438	132	1/12/2005	SWS
438	601	1/12/2005	SWS
438	612	1/12/2005	SWS
438	613	1/12/2005	SWS
438	958	1/12/2005	SWS

**INTERFERENCE SEARCHED**

Class	Subclass	Date	Examiner

**SEARCH NOTES  
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Key Words: Chip, Die, IC - Pad; Solder - Bump, Ball; Polyimide; Passivation; Fuse;	1/12/2005	SWS
ChipCarrier, Package Substrate, Wiring Substrate; Flip Chip Assembly; Underfilled.	1/12/2005	SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	1/12/2005	SWS